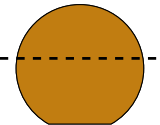


#1

Polished silicon wafer.



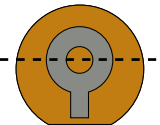
#2

Spin coating first layer of polyimide.



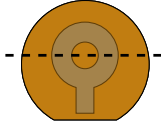
#3

Spin coating of **negative** resist. Patterning with Mask 1 (Metal).



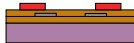
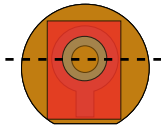
#4

Evaporation of Platinum. Lift-off.



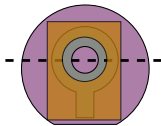
#5

Spin coating of second layer of polyimide.



#6

Spin coating of **positive** resist. Patterning of Mask 2 (PI).



#7

Reactive Ion Etching of PI. Release by peeling.